

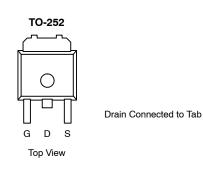
### SQD50N02-04L-GE3-VB Datasheet

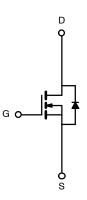
## N-Channel 20-V (D-S)175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>		
20	0.0045 @ V <sub>GS</sub> = 4.5 V	100		
	0.006 @ V <sub>GS</sub> = 2.5 V	90		

#### **FEATURES**

- Trench Power MOSFET
- 175°C Maximum Junction Temperature
- 100% R<sub>g</sub> Tested





N-Channel MOSFET

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V <sub>DS</sub>	20	v
Gate-Source Voltage		V <sub>GS</sub>	±15	V
	$T_{C} = 25^{\circ}C$		100	
Continuous Drain Current <sup>a</sup>	$T_{C} = 100^{\circ}C$	· I <sub>D</sub>	80	<u> </u>
Pulsed Drain Current		I <sub>DM</sub>	200	A
Continuous Source Current (Diode Conduction) <sup>a</sup>		IS	65	
	$T_{C} = 25^{\circ}C$		71	
Maximum Power Dissipation	T <sub>A</sub> = 25°C	P <sub>D</sub>	8.3 <sup>b, c</sup>	W
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
	$t \leq 10$ sec.		15	18	°C/W	
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	R <sub>thJA</sub>	40	50		
Maximum Junction-to-Case		R <sub>thJC</sub>	1.75	2.1		

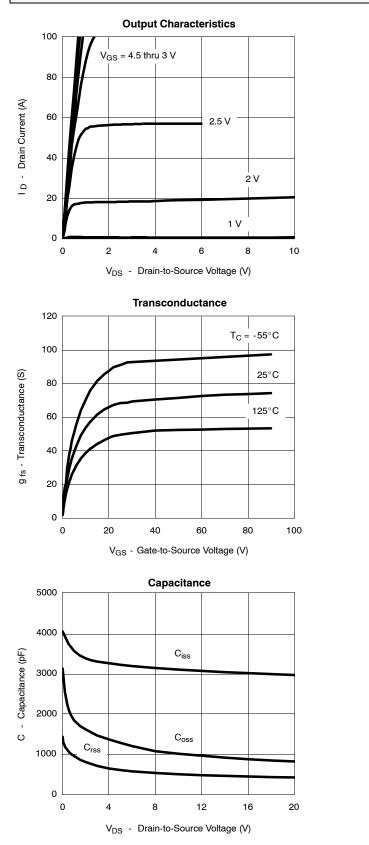
Notes

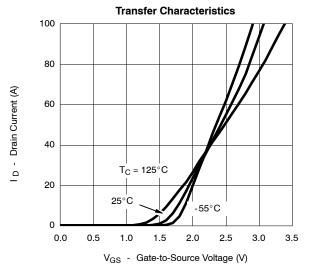
- a. Package Limited
- b. Surface Mounted on 1" x 1" FR4 Board
- c.  $t \leq 10 \text{ sec}$

Parameter Symbol		Test Condition	Test Condition Min		Max	Unit
Static	- H					
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu$ A	20			v
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	0.5		1.5	v
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = $\pm$ 12 V			±100	nA
7 0 0 0 0	1.	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1	
Zero Gate Voltage Drain Current	DSS	$V_{DS}$ = 20 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 $^{\circ}C$			50	μΑ
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS}$ = 5 V, $V_{GS}$ = 4.5 V	100			Α
		$V_{GS}$ = 4.5 V, I <sub>D</sub> = 20 A		0.0045		
Drain-Source On-State Resistance <sup>b</sup>	r <sub>DS(on)</sub>	$V_{GS}$ = 4.5 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.0055		Ω
		$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		0.006		
Forward Transconductanceb	9 <sub>fs</sub>	$V_{DS} = 5 \text{ V}, \text{ I}_{D} = 40 \text{ A}$	20			S
Dynamic <sup>a</sup>	· · ·		·			
Input Capacitance	C <sub>iss</sub>			3660		pF
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 20 V, f = 1 MHz		730		
Reverse Transfer Capacitance	C <sub>rss</sub>			375		
Total Gate Charge <sup>c</sup>	Qg			26	35	nC
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 10 V, $~V_{GS}$ = 4.5 V, $I_{D}$ = 40 A		5		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			7		
Gate Resistance	Rg		1		3.7	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			20	35	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 10 V, $R_L$ = 0.25 $\Omega$		120	190	- ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 40$ Å, $V_{GEN} = 4.5$ V, $R_G = 2.5 \Omega$		45	70	
Fall Time <sup>c</sup>	t <sub>f</sub>			20	35	
Source-Drain Diode Ratings an	d Characteristi	ic (T <sub>C</sub> = 25°C)				
Pulsed Current	I <sub>SM</sub>				100	А
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	I <sub>F</sub> = 100 A, V <sub>GS</sub> = 0 V		1.2	1.5	V
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 40 A, di/dt = 100 A/μs		35	70	ns



#### TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)





C 0.009  $V_{GS} = 4.5 V$ 0.006 0.003 0.003 0.000 0.000

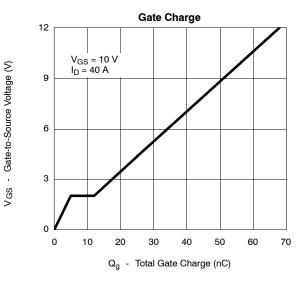
I<sub>D</sub> - Drain Current (A)

100

90

0

80

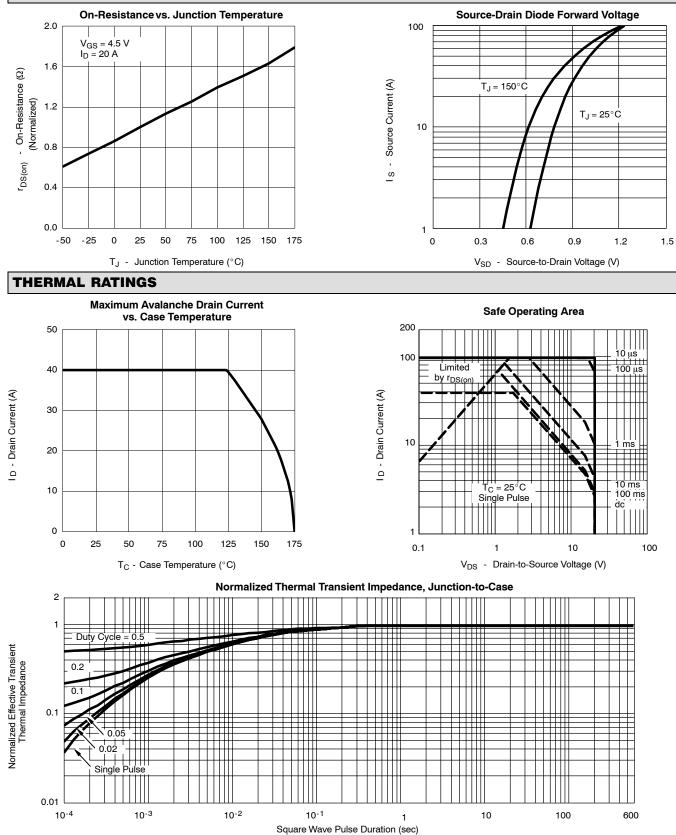


120

110

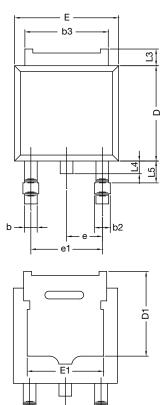


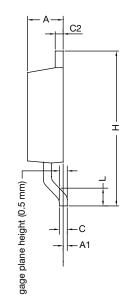






## **TO-252AA CASE OUTLINE**





	MILLIN	<b>IETERS</b>	INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
E	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28	BSC	0.090 BSC			
e1	4.56	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: X12- DWG: 534	0247-Rev. M, 7	24-Dec-12				

Note

• Dimension L3 is for reference only.



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